PRELIMINARY

TP3054-X, TP3057-X Extended Temperature "Enhanced" Serial Interface CODEC/Filter COMBO® Family

General Description

The TP3054, TP3057 family consists of μ -law and A-law monolithic PCM CODEC/filters utilizing the A/D and D/A conversion architecture shown in *Figure 1*, and a serial PCM interface. The devices are fabricated using National's advanced double-poly CMOS process (microCMOS).

The encode portion of each device consists of an input gain adjust amplifier, an active RC pre-filter which eliminates very high frequency noise prior to entering a switched-capacitor band-pass filter that rejects signals below 200 Hz and above 3400 Hz. Also included are auto-zero circuitry and a companding coder which samples the filtered signal and encodes it in the companded µ-law or A-law PCM format. The decode portion of each device consists of an expanding decoder, which reconstructs the analog signal from the companded µ-law or A-law code, a low-pass filter which corrects for the sin x/x response of the decoder output and rejects signals above 3400 Hz followed by a single-ended power amplifier capable of driving low impedance loads. The devices require two 1.536 MHz, 1.544 MHz or 2.048 MHz transmit and receive master clocks, which may be asynchronous; transmit and receive bit clocks, which may vary from 64 kHz to 2.048 MHz; and transmit and receive frame sync pulses. The timing of the frame sync pulses and PCM data is compatible with both industry standard formats.

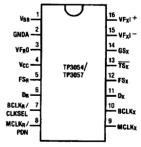
Features

- -40°C to +85°C operation
- Complete CODEC and filtering system (COMBO) including:
 - Transmit high-pass and low-pass filtering
 - Receive low-pass filter with sin x/x correction
 - Active RC noise filters
 - μ-law or A-law compatible COder and DECoder
 - Internal precision voltage reference
- Serial I/O interface
- Internal auto-zero circuitry
- μ-law, 16-pin—TP3054
- A-law, 16-pin—TP3057
- Designed for D3/D4 and CCITT applications
- ±5V operation
- Low operating power—typically 50 mW
- Power-down standby mode—typically 3 mW
- Automatic power-down
- TTL or CMOS compatible digital interfaces
- Maximizes line interface card circuit density
- Dual-In-Line or PCC surface mount packages
- See also AN-370, "Techniques for Designing with CODEC/Filter COMBO Circuits"

Connection Diagrams

Top View
Order Number TP3057V-X
NS Package Number V20A





Top View

Ti /H/8674_1

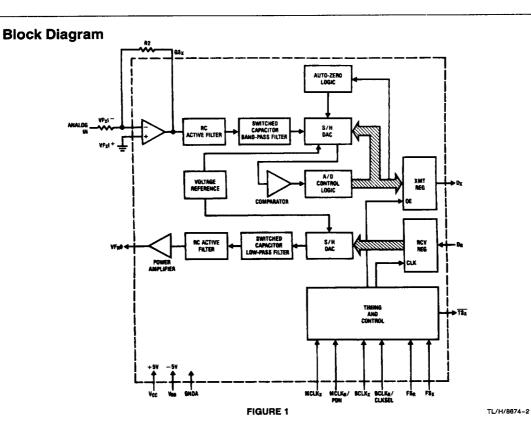
Order Number TP3054J-X or TP3057J-X NS Package Number J16A

Order Number TP3054N-X or TP3057N-X NS Package Number N16A

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TL/H/8674-8

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Symbol

Oynabol .		-,	
V _{BB}	Negative power supply pin. $V_{BB} = -5V \pm 5\%$.		synchronous with MCLK _X for best performance. When MCLK _R is connected continuously low,
GNDA	Analog ground. All signals are referenced to this pin.		$MCLK_X$ is selected for all internal timing. When $MCLK_B$ is connected continuously high, the device is powered down.
VF _R O	Analog output of the receive power amplifier.	MCLKX	Transmit master clock. Must be 1.536 MHz, 1.544
Vcc	Positive power supply pin. $V_{CC} = +5V \pm 5\%$.		MHz or 2.048 MHz. May be asynchronous with MCLK _R . Best performance is realized from synchronous operation.
FS _R	Receive frame sync pulse which enables BCLK _R to shift PCM data into D _R . FS _R is an 8 kHz pulse train. See <i>Figures 2</i> and <i>3</i> for timing details.	FS _X	Transmit frame sync pulse input which enables $BCLK_X$ to shift out the PCM data on D_X . FS_X is an 8 kHz pulse train, see <i>Figures 2</i> and <i>3</i> for timing details.
D _R	Receive data input. PCM data is shifted into D _R following the FS _R leading edge.	BCLKX	The bit clock which shifts out the PCM data on D _X . May vary from 64 kHz to 2.048 MHz, but must be
BCLKR/CLKSEL	The bit clock which shifts data into D _R af-		synchronous with MCLK _X .
	ter the FS _R leading edge. May vary from 64 kHz to 2.048 MHz. Alternatively, may be a logic input which selects either 1.536	D_X	The TRI-STATE® PCM data output which is enabled by FS _X .
	MHz/1.544 MHz or 2.048 MHz for master clock in synchronous mode and BCLKx is	TSX	Open drain output which pulses low during the encoder time slot.
	used for both transmit and receive directions (see Table 1).	GS _X	Analog output of the transmit input amplifier. Used to externally set gain.
MCLK _R /PDN	Receive master clock. Must be 1.536	VF _X I-	Inverting input of the transmit input amplifier.
	MHz, 1.544 MHz or 2.048 MHz. May be asynchronous with MCLK _X , but should be	VF _X I+	Non-inverting input of the transmit input amplifier.

Symbol

Function

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Function

Functional Description

POWER-UP

When power is first applied, power-on reset circuitry initializes the COMBO and places it into a power-down state. All non-essential circuits are deactivated and the D_X and VF_RO outputs are put in high impedance states. To power-up the device, a logical low level or clock must be applied to the MCLK_R/PDN pin and FS_X and/or FS_R pulses must be present. Thus, 2 power-down control modes are available. The first is to pull the MCLK_R/PDN pin high; the alternative is to hold both FS_X and FS_R inputs continuously low—the device will power-down approximately 1 ms after the last FS_X or FS_R pulse. Power-up will occur on the first FS_X or FS_R pulse. The TRI-STATE PCM data output, D_X, will remain in the high impedance state until the second FS_X pulse.

SYNCHRONOUS OPERATION

For synchronous operation, the same master clock and bit clock should be used for both the transmit and receive directions. In this mode, a clock must be applied to MCLK $_{\rm X}$ and the MCLK $_{\rm R}$ /PDN pin can be used as a power-down control. A low level on MCLK $_{\rm R}$ /PDN powers up the device and a high level powers down the device. In either case, MCLK $_{\rm X}$ will be selected as the master clock for both the transmit and receive circuits. A bit clock must also be applied to BCLK $_{\rm X}$ and the BCLK $_{\rm R}$ /CLKSEL can be used to select the proper internal divider for a master clock of 1.536 MHz, 1.544 MHz or 2.048 MHz. For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame.

With a fixed level on the BCLK $_{\rm R}$ /CLKSEL pin, BCLK $_{\rm X}$ will be selected as the bit clock for both the transmit and receive directions. Table I indicates the frequencies of operation which can be selected, depending on the state of BCLK $_{\rm R}$ /CLKSEL. In this synchronous mode, the bit clock, BCLK $_{\rm X}$, may be from 64 kHz to 2.048 MHz, but must be synchronous with MCLK $_{\rm X}$.

Each FS $_{\rm X}$ pulse begins the encoding cycle and the PCM data from the previous encode cycle is shifted out of the enabled D $_{\rm X}$ output on the positive edge of BCLK $_{\rm X}$. After 8 bit clock periods, the TRI-STATE D $_{\rm X}$ output is returned to a high impedance state. With an FS $_{\rm R}$ pulse, PCM data is latched via the D $_{\rm R}$ input on the negative edge of BCLK $_{\rm X}$ (or BCLK $_{\rm R}$ if running). FS $_{\rm X}$ and FS $_{\rm R}$ must be synchronous with MCLK $_{\rm X/R}$.

TABLE I. Selection of Master Clock Frequencies

BCLK _R /CLKSEL	Master Clock Frequency Selected						
	TP3057	TP3054					
Cłocked	2.048 MHz	1.536 MHz or					
0	1.536 MHz or	1.544 MHz 2.048 MHz					
	1.544 MHz	2.040 10172					
1	2.048 MHz	1.536 MHz or					
		1.544 MHz					

ASYNCHRONOUS OPERATION

For asynchronous operation, separate transmit and receive clocks may be applied. MCLKX and MCLKR must be 2.048 MHz for the TP3057, or 1.536 MHz, 1.544 MHz for the TP3054, and need not be synchronous. For best transmission performance, however, MCLKR should be synchronous with MCLKx, which is easily achieved by applying only static logic levels to the MCLK_R/PDN pin. This will automatically connect MCLKX to all internal MCLKR functions (see Pin Description). For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame. FS_X starts each encoding cycle and must be synchronous with MCLKX and BCLKX. FSR starts each decoding cycle and must be synchronous with BCLKR. BCLKR must be a clock, the logic levels shown in Table I are not valid in asynchronous mode. BCLKX and BCLKR may operate from 64 kHz to 2.048 MHz.

SHORT FRAME SYNC OPERATION

The COMBO can utilize either a short frame sync pulse or a long frame sync pulse. Upon power initialization, the device assumes a short frame mode. In this mode, both frame sync pulses, FS_X and FS_B , must be one bit clock period long, with timing relationships specified in $\mathit{Figure 2}$. With FS_X high during a falling edge of BCLK_X , the next rising edge of BCLK_X enables the D_X TRI-STATE output buffer, which will output the sign bit. The following seven rising edges clock out the remaining seven bits, and the next falling edge disables the D_X output. With FS_B high during a falling edge of BCLK_R (BCLK_X in synchronous mode), the next falling edge of BCLK_B (latches in the sign bit. The following seven falling edges latch in the seven remaining bits. All four devices may utilize the short frame sync pulse in synchronous or asynchronous operating mode.

LONG FRAME SYNC OPERATION

To use the long frame mode, both the frame sync pulses, FS_X and FS_R, must be three or more bit clock periods long, with timing relationships specified in Figure 3. Based on the transmit frame sync, FSX, the COMBO will sense whether short or long frame sync pulses are being used. For 64 kHz operation, the frame sync pulse must be kept low for a minimum of 160 ns. The D_X TRI-STATE output buffer is enabled with the rising edge of FSX or the rising edge of BCLKX, whichever comes later, and the first bit clocked out is the sign bit. The following seven BCLKX rising edges clock out the remaining seven bits. The DX output is disabled by the falling BCLKX edge following the eighth rising edge, or by FS_X going low, whichever comes later. A rising edge on the receive frame sync pulse, FSR, will cause the PCM data at D_R to be latched in on the next eight falling edges of BCLK_R (BCLK_X in synchronous mode). All four devices may utilize the long frame sync pulse in synchronous or asynchronous mode.

Functional Description (Continued)

In applications where the LSB bit is used for signalling, with FS_R two bit clock periods long, the decoder will interpret the lost LSB as "1/" to minimize noise and distortion.

TRANSMIT SECTION

The transmit section input is an operational amplifier with provision for gain adjustment using two external resistors, see Figure 4. The low noise and wide bandwidth allow gains in excess of 20 dB across the audio passband to be realized. The op amp drives a unity-gain filter consisting of RC active pre-filter, followed by an eighth order switched-capacitor bandpass filter clocked at 256 kHz. The output of this filter directly drives the encoder sample-and-hold circuit. The A/D is of companding type according to μ -law (TP3054) or A-law (TP3057) coding conventions. A precision voltage reference is trimmed in manufacturing to provide an input overload (t_{MAX}) of nominally 2.5V peak (see table of Transmission Characteristics). The FS_x frame sync pulse controls the sampling of the filter output, and then the successive-approximation encoding cycle begins. The 8-bit code is then loaded into a buffer and shifted out through D_X at the next FS $_X$ pulse. The total encoding delay will be approximately 165 μ s (due to the transmit filter) plus 125 μ s (due to encoding delay), which totals 290 μ s. Any offset voltage due to the filters or comparator is cancelled by sign bit integration.

RECEIVE SECTION

The receive section consists of an expanding DAC which drives a fifth order switched-capacitor low pass filter clocked at 256 kHz. The decoder is A-law (TP3057) or μ -law (TP3054) and the 5th order low pass filter corrects for the sin x/x attenuation due to the 8 kHz sample/hold. The filter is then followed by a 2nd order RC active post-filter/power amplifer capable of driving a 600 Ω load to a level of 7.2 dBm. The receive section is unity-gain. Upon the occurrence of FSR, the data at the DR input is clocked in on the falling edge of the next eight BCLKR, (BCLKx) periods. At the end of the decoder time slot, the decoding cycle begins, and 10 μ s later the decoder DAC output is updated. The total decoder delay is \sim 10 μ s (decoder update) plus 110 μ s (filter delay) plus 62.5 μ s (½ frame), which gives approximately 180 μ s.

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Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

V_{CC} to GNDA VBB to GNDA Voltage at any Analog Input

or Output V_{CC} + 0.3V to V_{BB} - 0.3V Voltage at any Digital Input or

Output V_{CC}+0.3V to GNDA-0.3V Operating Temperature Range -55°C to + 125°C

Storage Temperature Range -65°C to +150°C Lead Temperature (Soldering, 10 sec.) 300°C

Electrical Characteristics Unless otherwise noted, limits printed in BOLD characters are guaranteed for VCC = ± 5.0 V $\pm 5\%$, V_{BB} = -5.0V $\pm 5\%$; T_A = -40°C to ± 85 °C by correlation with 100% electrical testing at T_A = ± 25 °C. All other limits are assured by correlation with other production tests and/or product design and characterization. All signals referenced to GNDA. Typicals specified at $V_{CC} = +5.0V$, $V_{BB} = -5.0V$, $T_A = 25^{\circ}C$.

7V

-7V

Symbol	Parameter	Conditions	Min	Тур	Max	Uni
DIGITAL II	NTERFACE			<u> </u>	·	
V _{IL}	Input Low Voltage			1	0.6	V
V _{IH}	Input High Voltage		2.2			V
V _{OL}	Output Low Voltage	D _X , I _L = 3.2 mA SiG _P , I _L = 1.0 mA TS _X , I _L = 3.2 mA, Open Drain			0.4 0.4 0.4	\ \ \
VOH	Output High Voltage	D_X , $I_H = -3.2 \text{ mA}$ SIG _H , $I_H = -1.0 \text{ mA}$	2.4 2.4			V
կլ	Input Low Current	GNDA≤V _{IN} ≤V _{IL} , All Digital Inputs	-10	1	10	μ.
l _{IH}	Input High Current	V _{IH} ≤ V _{IN} ≤ V _{CC}	-10		10	<u>, , , , , , , , , , , , , , , , , , , </u>
loz	Output Current in High Impedance State (TRI-STATE)	D _X , GNDA≤V _O ≤V _{CC}	-10		10	μ/
ANALOG I	NTERFACE WITH TRANSMIT INPUT	AMPLIFIER (ALL DEVICES)	·		L	٠
I _I XA	Input Leakage Current	$-2.5V \le V \le +2.5V$, VF_XI^+ or VF_XI^-	-200		200	n/
R _I XA	Input Resistance	-2.5V≤V≤+2.5V, VF _X I+ or VF _X I-	10			Ms
R _O XA	Output Resistance	Closed Loop, Unity Gain		1	3	Ω
R _L XA	Load Resistance	GS _X	10			ks
C _L XA	Load Capacitance	GS _X			50	ρF
V _O XA	Output Dynamic Range	GS _X , R _L ≥ 10 kΩ	- 2.8		2.8	V
A _V XA	Voltage Gain	VF _X I+ to GS _X	5000	1		٧/
F _U XA	Unity Gain Bandwidth		1	2		МН
VosXA	Offset Voltage		-20		20	m\
V _{CM} XA	Common-Mode Voltage	CMRRXA > 60 dB	-2.5		2.5	٧
CMRRXA	Common-Mode Rejection Ratio	DC Test	60			dE
PSRRXA	Power Supply Rejection Ratio	DC Test	60		-	d₿
ANALOG II	TERFACE WITH RECEIVE FILTER (A	ALL DEVICES)				
RORF	Output Resistance	Pin VF _B O		1	3	Ω
RLRF	Load Resistance	VF _R O = ±2.5V	600			Ω
C _L RF	Load Capacitance				500	pF
VOS _R O	Output DC Offset Voltage		-200		200	m۷
POWER DI	SSIPATION (ALL DEVICES)				<u></u> 1	
lcc0	Power-Down Current	No Load (Note)		0.65	2.0	mA
l _{BB} 0	Power-Down Current	No Load (Note)		0.01	0.33	mA
lcc1	Power-Up (Active) Current	No Load	, , , , ,	5.0	11.0	mA
BB1	Power-Up (Active) Current	No Load		5.0	11.0	mA

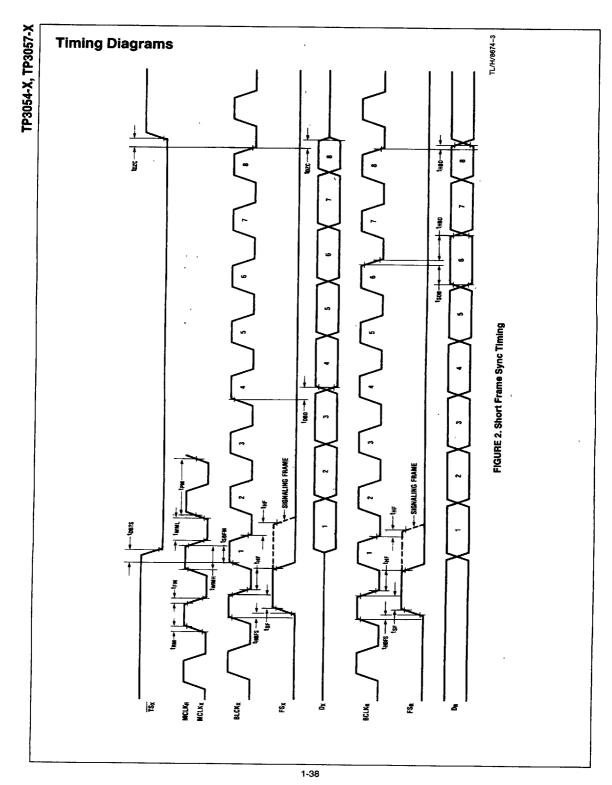
Note: ICC0 and IBB0 are measured after first achieving a power-up state.

Timing Specifications Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for $V_{CC} = +5.0V \pm 5\%$, $V_{BB} = -5.0V \pm 5\%$; $T_A = -40^{\circ}C$ to $+85^{\circ}C$ by correlation with 100% electrical testing at $T_A = 25^{\circ}C$. All other limits are assured by correlation with other production tests and/or product design and characterization. All signals referenced to GNDA. Typicals specified at $V_{CC} = +5.0V$, $V_{BB} = 5.0V$, $T_A = 25^{\circ}C$.

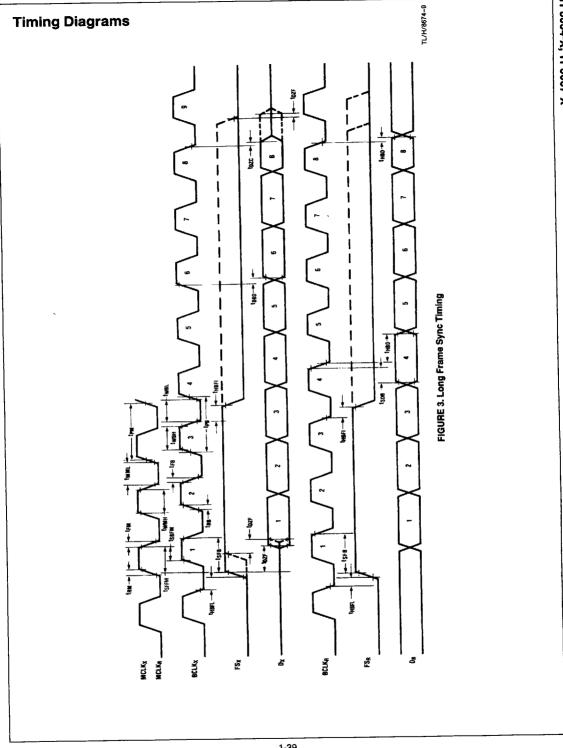
All timing parameters are assured at $V_{OH} = 2.0 V$ and $V_{OL} = 0.7 V$.

See Definitions and Timing Conventions section for test methods information.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
1/t _{PM}	Frequency of Master Clocks	Depends on the Device Used and the BCLK _R /CLKSEL Pin. MCLK _X and MCLK _R		1.536 1.544 2.048		MHz MHz MHz
t _{RM}	Rise Time of Master Clock	MCLK _X and MCLK _R			50	ns
t _{FM}	Fall Time of Master Clock	MCLK _X and MCLK _R			50	ns
t _{PB}	Period of Bit Clock		485	488	15725	ns
t _{RB}	Rise Time of Bit Clock	BCLK _X and BCLK _R			50	ns
t _{FB}	Fall Time of Bit Clock	BCLK _X and BCLK _R			50	ns
t _{WMH}	Width of Master Clock High	MCLK _X and MCLK _R	160			ns
twmL	Width of Master Clock Low	MCLK _X and MCLK _R	160			ns
tsbfm	Set-Up Time from BCLK _X High to MCLK _X Falling Edge	First Bit Clock after the Leading Edge of FSx Short Frame Long Frame	100 125			ns
tsffm	Setup Time from FS _X High to MCLK _X Falling Edge	Long Frame Only	100			ns
twBH	Width of Bit Clock High	V _{IH} = 2.2V	160			ns
t _{WBL}	Width of Bit Clock Low	V _{IL} =0.6V	160			ns
tHBFL	Holding Time from Bit Clock Low to Frame Sync	Long Frame Only	0			ns
tHBFS	Holding Time from Bit Clock High to Frame Sync	Short Frame Only	0			ns
tsfB	Set-Up Time from Frame Sync to Bit Clock Low	Long Frame Only	115			ns
t _{DBD}	Delay Time from BCLK _X High to Data Valid	Load = 150 pF plus 2 LSTTL Loads	0		140	ns
t _{DBTS}	Delay Time to TS _X Low	Load = 150 pF plus 2 LSTTL Loads			140	ns
t _{DZC}	Delay Time from BCLK _X Low to Data Output Disabled	C _L = 0 pF to 150 pF	50		165	ns
^t DZF	Delay Time to Valid Data from FS _X or BCLK _X , Whichever Comes Later	C _L = 0 pF to 150 pF	20		165	ns
t _{SDB}	Set-Up Time from D _R Valid to BCLK _{R/X} Low		50		<u> </u>	ns
t _{HBD}	Hold Time from BCLK _{R/X} Low to D _R Invalid		50			ns
t _{SF}	Set-Up Time from FS _{X/R} to BCLK _{X/R} Low	Short Frame Sync Pulse (1 Bit Clock Period Long)	50			n
t _{HF}	Hold Time from BCLK _{X/R} Low to FS _{X/R} Low	Short Frame Sync Pulse (1 Bit Clock Period Long)	100			n
t _{HBFI}	Hold Time from 3rd Period of Bit Clock Low to Frame Sync (FS _X or FS _R)	Long Frame Sync Pulse (from 3 to 8 Bit Clock Periods Long)	100			n
t _{WFL}	Minimum Width of the Frame Sync Pulse (Low Level)	64k Bit/s Operating Mode	160			l n



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Transmission Characteristics

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for $V_{CC} = +5.0V \pm 5\%$, $V_{BB} = -5.0V \pm 5\%$; $T_A = -40^{\circ}$ C to $+85^{\circ}$ C by correlation with 100% electrical testing at $T_A = 25^{\circ}$ C. All other limits are assured by correlation with other production tests and/or product design and characterization. GNDA = 0V, f = 1.02 kHz, $V_{IN} = 0$ dBm0, transmit input amplifier connected for unity gain non inverting. Typicals are specified at $V_{CC} = +5.0V$, $V_{CD} = -5.0V$, V_{CD

	Parameter	Conditions	Min	Тур	Max	Uni
AMPLIT	UDE RESPONSE			1 -76		
	Absolute Levels (Definition of Nominal Gain)	Nominal 0 dBm0 Level is 4 dBm (600Ω) 0 dBm0		1.2276		Vrm
t _{MAX}		Max Overload Level TP3054 (3.17 dBm0) TP3057 (3.14 dBm0)		2.501 2.492		V _P
G _{XA}	Transmit Gain, Absolute	$T_A = 25$ °C, $V_{CC} = 5V$, $V_{BB} = -5V$ Input at $GS_X = 0$ dBm0 at 1020 Hz	-0.15		0.15	dE
G _{XP}	Transmit Gain, Relative to G _{XA}	f= 16 Hz f= 50 Hz f= 60 Hz f= 200 Hz f= 300 Hz - 3000 Hz f= 3152 Hz f= 3300 Hz f= 3400 Hz f= 4600 Hz and Up, Measure Response from 0 Hz to 4000 Hz	-1.8 -0.15 -0.15 -0.35 -0.7		-40 -30 -26 -0.1 0.15 0.20 0.1 0 -14	dE dE dE dE dE dE
G _{XAT}	Absolute Transmit Gain Variation with Temperature	Relative to G _{XA}	-0.15		0.15	dB
G _{XAV}	Absolute Transmit Gain Variation with Supply Voltage	Relative to G _{XA}	-0.05		0.05	d₿
G _{XRL}	Transmit Gain Variations with Level	Sinusoidal Test Method Reference Level = -10 dBm0 VF _X I + = -40 dBm0 to $+3 \text{ dBm0}$ VF _X I + = -50 dBm0 to -40 dBm0 VF _X I + = -55 dBm0 to -50 dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB dB
G _{FIA}	Receive Gain, Absolute	T _A =25°C, V _{CC} =5V, V _{BB} = -5V Input=Digital Code Sequence for 0 dBm0 Signal at 1020 Hz	-0.20		0.20	dB
G _{RR}	Receive Gain, Relative to G _{RA}	f=0 Hz to 3000 Hz f=3300 Hz f=3400 Hz f=4000 Hz	-0.15 -0.35 -0.7		0.15 0.1 0 -14	dB dB dB
GRAT	Absolute Receive Gáin Variation with Temperature	Relative to GRA	-0.15		0.15	dB
3RAV	Absolute Receive Gain Variation with Supply Voltage.	Relative to G _{RA}	-0.05		0.05	dB
3AAL	Receive Gain Variations with Level	Sinusoidal Test Method; Reference Input PCM Code Corresponds to an Ideally Encoded PCM Level = -40 dBm0 to +3 dBm0 PCM Level = -50 dBm0 to -40 dBm0 PCM Level = -55 dBm0 to -50 dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB dB
/RO	Receive Output Drive Level	R _L =600Ω	-2.5			

Transmission Characteristics (Continued)

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for $V_{CC}=+5.0V\pm5\%$, $V_{BB}=-5.0V\pm5\%$; $T_A=-40^{\circ}C$ to $+85^{\circ}C$ by correlation with 100% electrical testing at $T_A=25^{\circ}C$. All other limits are assured by correlation with other production tests and/or product design and characterization. GNDA = 0V, f = 1.02 kHz, $V_{IN}=0$ dBm0, transmit input amplifier connected for unity gain non inverting. Typicals are specified at $V_{CC}=+5.0V$, $V_{BB}=-5.0V$, $V_{AB}=-5.0V$

Symbol	Parameter	Conditions	Min	Тур	Max	Units
	E DELAY DISTORTION WITH FREQU	ENCY				
DXA	Transmit Delay, Absolute	f=1600 Hz		290	315	μs
	Transmit Delay, Relative to D _{XA}	f=500 Hz-600 Hz		195	220	μs
D _{XR}	Transmit Delay, Relative to DXA	f=600 Hz-800 Hz		120	145	μs
1		f=800 Hz-1000 Hz		50	75	μs
ļ		f= 1000 Hz-1600 Hz		20	40	μs
		f= 1600 Hz-2600 Hz		55	75	μs
		f= 2600 Hz-2800 Hz		80	105	μs
1		f=2800 Hz-3000 Hz		130	155	μs
	Deschie Detay Absolute	f=1600 Hz		180	200	μs
D _{RA}	Receive Delay, Absolute	f=500 Hz-1000 Hz	-40	-25		μs
DRR	Receive Delay, Relative to D _{RA}	f= 1000 Hz-1600 Hz	-30	-20		μS
		f=1600 Hz-2600 Hz		70	90	μs
		f=2600 Hz-2800 Hz		100	125	μs
		f=2800 Hz-2800 Hz	ļ	145	175	μs
		1-2800 H2-3000 H2			,,,,	F
NOISE			Ι	12	16	dBrnC0
N _{XC}	Transmit Noise, C Message	TP3054]	'-	.	abiliou
	Weighted	(Note 1)		.		
N _{XP}	Transmit Noise, P Message	TP3057		-74	-67	dBm0p
- 'Ai	Weighted	(Note 1)				
N _{RC}	Receive Noise, C Message	PCM Code is Alternating Positive			1	i
THG	Weighted	and Negative Zero —]]
	170,3	TP3054	ļ	8	11	dBrnC0
N	Receive Noise, P Message	TP3057 PCM Code Equals Positive	T			ļ
NRP	Weighted	Zero —	l	-82	-79	dBm0p
N _{RS}	Noise, Single Frequency	f=0 kHz to 100 kHz, Loop Around			-53	dBm0
כאיי	, tolog, on give to quest,	Measurement, VF _X I+=0 Vrms				
PPSRX	Positive Power Supply Rejection,	V _{CC} =5.0 V _{DC} +100 mVrms				
	Transmit	f=0 kHz-50 kHz (Note 2)	40	ļ		dBC
NPSRX	Negative Power Supply Rejection,	$V_{BB} = -5.0 V_{DC} + 100 \text{ mVrms}$	1	i		
^	Transmit	f = 0 kHz-50 kHz (Note 2)	40		 	dBC
PPSRR	Positive Power Supply Rejection,	PCM Code Equals Positive Zero		Ì		
	Receive	V _{CC} = 5.0 V _{DC} + 100 mVrms	Į	İ	1	
		Measure VF _R 0		1	İ	_
		f=0 Hz-4000 Hz	38			dBC
		f = 4 kHz-25 kHz	38	Į.		dB
		f = 25 kHz-50 kHz	35			dB
NPSRR	Negative Power Supply Rejection,	PCM Code Equals Positive Zero				
MESUR	Receive	V _{BB} = -5.0 V _{DC} + 100 mVrms	1			Í
	1 ISCOIVE	Measure VF _B 0	1			
		f=0 Hz-4000 Hz	38			dBC
		f = 4 kHz - 25 kHz	38			dB
		f = 25 kHz - 50 kHz	35	1	1	l dB

Transmission Characteristics (Continued)

Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for $V_{CC}=+5.0V\pm5\%$, $V_{BB}=-5.0V\pm5\%$; $T_A=-40^{\circ}C$ to $+85^{\circ}C$ by correlation with 100% electrical testing at $T_A=25^{\circ}C$. All other limits are assured by correlation with other production tests and/or product design and characterization. GNDA = 0V, f = 1.02 kHz, V_{IN} = 0 dBm0, transmit input amplifier

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
sos	Spurious Out-of-Band Signals at the Channel Output	Loop Around Measurement, 0 dBm0, 300 Hz to 3400 Hz Input PCM Code Applied at D _R .			-30	dB
		4600 Hz-7600 Hz		j	-30	dB
		7600 Hz-8400 Hz		1	-40	dB
		8400 Hz-100,000 Hz			-30	dB
DISTORT	ION	1			_L	
STDX	Signal to Total Distortion	Sinusoidal Test Method (Note 3)		1		· · · · ·
STDR	Transmit or Receive	Level = 3.0 dBm0	33			dB0
	Half-Channel	= 0 dBm0 to -30 dBm0	36	•		dB
		= -40 dBm0 XMT	28			dB0
		RCV	29			dB0
		= -55 dBm0 XMT	13		1 1	dBC
		RCV	14		i i	dBC
SFD _X	Single Frequency Distortion, Transmit				-43	dB
SFD _R	Single Frequency Distortion, Receive		_		-43	dB
IMD	Intermodulation Distortion	Loop Around Measurement, VFx+ = -4 dBm0 to -21 dBm0, Two Frequencies in the Range 300 Hz-3400 Hz			-41	dB
CROSSTA	LK		1		<u> </u>	
CT _{X-R}	Transmit to Receive Crosstalk, 0 dBm0 Transmit Level	f=300 Hz-3400 Hz D _R = Quiet PCM Code (Note 4)		-90	-70	dB
CT _{R-X}	Receive to Transmit Crosstalk, 0 dBm0 Receive Level	f=300 Hz-3400 Hz, VF _X I = Multitone (Note 2)		-90	-70	dB

· · · · · · · · · · · · · · · · · · ·				TP3 μ-L						(Inc	ludes	A-L	:057 _aw n Bit I	nvers	ion)	
V_{IN} (at GS_X) = + Full-Scale	1	0	0	0	_0	0	0	0	1	0	1	0	1	0	1	
V _{IN} (at GS _X) = 0V	[1	1	1	1	1	1	1	1	1	1	0	1	0	1	0	-
	lo	1	1	1	1	1	1	1	0	1	0	1	0	1	0	1
V _{IN} (at GS _X) = - Full-Scale	0	0	0	0	0	0	0	0	0	0	1	0	1	0	-	_

sing C message weighted filter for μ -law and psophometric weighted filter for A-law.

Note 4: CT_{X-R} @ 1.544 MHz MCLK_X freq. is -70 dB max. 50% $\pm 5\%$ BCLK_X duty cycle.

Applications Information

POWER SUPPLIES

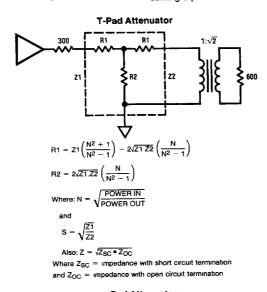
While the pins of the TP3050 family are well protected against electrical misuse, it is recommended that the standard CMOS practice be followed, ensuring that ground is connected to the device before any other connections are made. In applications where the printed circuit board may be plugged into a "hot" socket with power and clocks already present, an extra long ground pin in the connector should

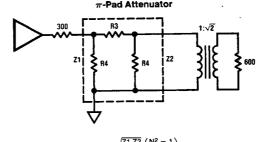
All ground connections to each device should meet at a common point as close as possible to the GNDA pin. This minimizes the interaction of ground return currents flowing through a common bus impedance. 0.1 μF supply decoupling capacitors should be connected from this common ground point to V_{CC} and V_{BB} , as close to device pins as possible.

For best performance, the ground point of each CODEC/ FILTER on a card should be connected to a common card ground in star formation, rather than via a ground bus. This common ground point should be decoupled to V_{CC} and V_{BB} with 10 μF capacitors.

RECEIVE GAIN ADJUSTMENT

For applications where a TP3050 family CODEC/filter receive output must drive a 600 Ω load, but a peak swing lower than $\pm 2.5 V$ is required, the receive gain can be easily adjusted by inserting a matched T-pad or π -pad at the output. Table II lists the required resistor values for 600Ω terminations. As these are generally non-standard values, the equations can be used to compute the attenuation of the closest practical set of resistors. It may be necessary to use unequal values for the R1 or R4 arms of the attenuators to achieve a precise attenuation. Generally it is tolerable to allow a small deviation of the input impedance from nominal while still maintaining a good return loss. For example a 30 dB return loss against 600Ω is obtained if the output impedance of the attenuator is in the range 282Ω to 319Ω (assuming a perfect transformer).





TL/H/8674-5

$$R3 = \sqrt{\frac{Z1 \ Z2}{2}} \left(\frac{N^2 - 1}{N} \right)$$

 $R3 = Z1 \left(\frac{N^2 - 1}{N^2 - 2NS + 1} \right)$

Note: See Application Note 370 for further details.

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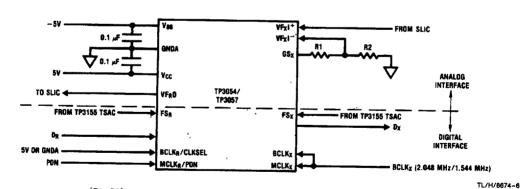
6501124 0088917 302

Applications Information (Continued)

TABLE II. Attentuator Tables for Z1 = Z2 = 300Ω (All Values in Ω)

(All Values in 11)										
dB	R1	R2	R3	R4						
0.1	1.7	26k	3.5	52k						
0.2	3.5	13k	6.9	26k						
0.3	5.2	8.7k	10.4	17.4k						
0.4	6.9	6.5k	13.8	13k						
0.5	8.5	5.2k	17.3	10.5k						
0.6	10.4	4.4k	21.3	8.7k						
0.7	12.1	3.7k	, 24.2	7.5k						
0.8	13.8	3.3k	27.7	6.5k						
0.9	15.5	2.9k	31.1	5.8k						
1.0	17.3	2.61	34.6	5.2k						
2	34.4	1.3k	70	2.6k						
3	51.3	850	107	1.8k						
4	68	650	144	1.3k						
5	84	494	183	1.1k						
6	100	402	. 224	900						
7	115	380	269	785						
8	379	284	317	698						
9	143	244	370	630						
10	156	211	427	527						
11	168	184	490	535						
12	180	161	550	500						
13	190	142	635	473						
14	200	125	720	450						
15	210	110	816	430						
16	218	98	924	413						
18	233	77	1.17k	386						
20	246	61	1.5k	366						

Typical Synchronous Application



Note 1: XMIT gain = $20 \times log \left(\frac{R1 + R2}{R2} \right)$,(R1 + R2) > 10 K Ω .

FIGURE 4